Supplier Name: **Texas Instruments Inc. (DUNS# 00-732-1904)**
Contact Info: ti.com/support
Form/Declaration Type: **Distribute - RoHS and IEC 62474 DB**
Created on: **05/16/2022**

Details for "74LVC16373ADGVRE4"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package | Pins	Package body size (mm)	Total device mass (mg)*
74LVC16373ADGVRE4	NIPDAU	Level-1-260C-UNLIM	TI MALAYSIA A/T	DGV | 48	4.4x9.7x1.05	114.7

***Total Device Mass**
The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

				Homogeneous Material Level		Component Level	
Component	**Substance**	**CAS Number**	**Amount (mg)**	**Percentage %**	**ppm**	**Percentage %**	**ppm**
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.336489	99.997623	999976	0.293418	2934
Copper and Its Alloys	Iron	7439-89-6	0.000001	0.000297	3	0.000001	0
Nickel and Its Alloys	Nickel	7440-02-0	0.000001	0.000297	3	0.000001	0
Other Nonferrous Metals and Alloys	Manganese	7439-96-5	0.000001	0.000297	3	0.000001	0
Precious Metals	Silver	7440-22-4	0.000005	0.001486	15	0.000004	0
Sub-Total			**0.336497**	**100**	**1000000**	**0.293425**	**2934**
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.430838	69.999984	700000	0.375691	3757
Thermoplastics	Epoxy	85954-11-6	0.184645	30.000016	300000	0.16101	1610
Sub-Total			**0.615483**	**100**	**1000000**	**0.536701**	**5367**
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	44.474513	97.424999	974250	38.781759	387818
Copper and Its Alloys	Iron	7439-89-6	1.0956	2.4	24000	0.955363	9554
Copper and Its Alloys	Phosphorus	7723-14-0	0.006848	0.015001	150	0.005971	60
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.013695	0.03	300	0.011942	119
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.013695	0.03	300	0.011942	119
Zinc and Its Alloys	Zinc	7440-66-6	0.04565	0.1	1000	0.039807	398
Sub-Total			**45.650001**	**100**	**1000000**	**39.806785**	**398068**
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.106534	95.119643	951196	0.092898	929
Precious Metals	Gold	7440-57-5	0.000874	0.780357	7804	0.000762	8
Precious Metals	Palladium	7440-05-3	0.004592	4.1	41000	0.004004	40
Sub-Total			**0.112**	**100**	**1000000**	**0.097664**	**977**
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	55.928464	85.5	855000	48.769601	487696
Other Nonferrous Metals and Alloys	Metal Hydroxide	Trade Secret	1.962402	3	30000	1.711214	17112
Other Organic Materials	Chlorine	7782-50-5	0.013083	0.02	200	0.011408	114
Other Plastics and Rubber	Carbon Black	1333-86-4	0.19624	0.3	3000	0.171121	1711
Other Plastics and Rubber	Organic Phosphorus	1330-78-5	0.065413	0.099999	1000	0.05704	570
Thermoplastics	Epoxy	85954-11-6	7.247806	11.080001	110800	6.320084	63201
Sub-Total			**65.413408**	**100**	**1000000**	**57.040468**	**570405**
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	2.551557	100	1000000	2.224957	22250
Sub-Total			**2.551557**	**100**	**1000000**	**2.224957**	**22250**
Total			114.678946			100	1000000

Important Note
The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.
See Glossary of Terms for more details.

Important Part Information
There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology
For an explanation of the methods used to determine material weights, See Product Content Methodology

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

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For additional information, please contact TI customer support.

Signature: (click here for a fuller statement with a signed certificate)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality
For further environmental statements, please go to www.ti.com/ecoinfo
Created on: 05/16/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

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Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb203) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.